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Patent



1765

Docket No. 1232-4421US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant(s) : UEHARA et al.
Serial No. : 09/664,715 Art Unit : 1765
Filed : September 19, 2000 Examiner : K. Chen
For : WAFER PROCESSING APPARATUS, WAFER PROCESSING
METHOD, AND SEMICONDUCTOR SUBSTRATE
FABRICATION METHOD

AMENDMENT

MAIL STOP - Non-Fee Amendment

COMMISSIONER FOR PATENTS

P.O. Box 1450

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Sir:

Kindly amend the above-identified application in response to the non-final Office Action dated August 4, 2003.

Amendments to the Claims are reflected in the listing of claims, which begins on Page 2 of this paper.

Remarks begin on Page 6 of this paper.